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Raumfahrttechnik - Elektromagnetische Kompatibilität

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European Foreword

This document (EN 16603-20-07:2022) has been prepared by Technical Committee CEN/CLC/JTC 5 "Space", the secretariat of which is held by DIN.

This standard (EN 16603-20-07:2022) originates from ECSS-E-ST-20-07C Rev.2.

This European Standard shall be given the status of a national standard, either by publication of an identical text or by endorsement, at the latest by April 2023, and conflicting national standards shall be withdrawn at the latest by April 2023.

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CEN [and/or CENELEC] shall not be held responsible for identifying any or all such patent rights.

This document supersedes EN 16603-20-07:2014.

The main changes with respect to EN 16603-20-07:2014 are listed below:

- Implementation of Change Requests.
- Specification of the maximum frequency step size for susceptibility tests, in clause 5.2.10.1.
- Addition of clause 5.2.12 "Power bus voltage".
- Addition of clause 5.2.13 "Photographic data".
- Specification of a method for conducted susceptibility to short transients coupled on EUT power leads in both differential and common mode, in clause 5.4.9.
- Specification of the radiated susceptibility tests to electric fields to follow a substitution method, in clause 5.4.11.
- Addition of clause 5.4.13 "Susceptibility to wire-coupled electrostatic discharges (current injection probe method)".
- Addition of clause 5.4.14 "Susceptibility to electrostatic discharges into the chassis".
- Addition of clause 5.4.15 "CE, power leads, time domain".

This document has been prepared under a standardization request given to CEN by the European Commission and the European Free Trade Association.

This document has been developed to cover specifically space systems and has therefore precedence over any EN covering the same scope but with a wider domain of applicability (e.g. : aerospace).

According to the CEN-CENELEC Internal Regulations, the national standards organizations of the following countries are bound to implement this European Standard: Austria, Belgium, Bulgaria, Croatia, Cyprus, Czech Republic, Denmark, Estonia, Finland, Former Yugoslav Republic of Macedonia, France,

Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, Netherlands, Norway, Poland, Portugal, Romania, Serbia, Slovakia, Slovenia, Spain, Sweden, Switzerland, Türkiye and the United Kingdom.

Introduction

Electromagnetic compatibility (EMC) of a space system or equipment is the ability to function satisfactorily in its electromagnetic environment without introducing intolerable electromagnetic disturbances to anything in that environment.

The space system is designed to be compatible with its external natural, induced, or man-made electromagnetic environment. Natural components are lightning for launchers, the terrestrial magnetic field for space vehicles. Spacecraft charging is defined as voltage building-up of a space vehicle or spacecraft units when immerged in plasma. Electrostatic discharges result from spacecraft charging with possible detrimental effects. External man-made interference, intentional or not, are caused by radar or telecommunication beams during ground operations and the launching sequence. Intersystem EMC also applies between the launcher and its payload or between space vehicles.

Intrasystem EMC is defined between all electrical, electronic, electromagnetic, and electromechanical equipment within the space vehicle and by the presence of its self-induced electromagnetic environment. It comprises the intentional radiated electromagnetic fields and parasitic emission from on-board equipment. Both conducted and radiated emissions are concerned. An electromagnetic interference safety margin is defined at system critical points by comparison of noise level and susceptibility at these points.

1 Scope

EMC policy and general system requirements are specified in ECSS-E-ST-20.

This ECSS-E-ST-20-07 Standard addresses detailed system requirements (Clause 4), general test conditions, verification requirements at system level, and test methods at subsystem and equipment level (Clause 5) as well as informative limits (Annex A).

Associated to this standard is ECSS-E-ST-20-06 "Spacecraft charging", which addresses charging control and risks arising from environmental and vehicle-induced spacecraft charging when ECSS-E-ST-20-07 addresses electromagnetic effects of electrostatic discharges.

Annexes A to C of the ECSS-E-ST-20 standard document EMC activities related to ECSS-E-ST-20-07: the EMC Control Plan (Annex A) defines the approach, methods, procedures, resources, and organization, the Electromagnetic Effects Verification Plan (Annex B) defines and specifies the verification processes, analyses and tests, and the Electromagnetic Effects Verification Report (Annex C) document verification results. The EMEVP and the EMEVR are the vehicles for tailoring this standard.

This standard may be tailored for the specific characteristic and constrains of a space project in conformance with ECSS-S-ST-00-02.

2 Normative references

The following normative documents contain provisions which, through reference in this text, constitute provisions of this ECSS Standard. For dated references, subsequent amendments to, or revision of any of these publications do not apply, However, parties to agreements based on this ECSS Standard are encouraged to investigate the possibility of applying the more recent editions of the normative documents indicated below. For undated references, the latest edition of the publication referred to applies.

EN reference	Reference in text	Title
EN 16601-00-010	ECSS-S-ST-00-01	ECSS system - Glossary of terms
EN 16603-20	ECSS-E-ST-20	Space engineering - Electrical and electronic
EN 16603-20-06	ECSS-E-ST-20-06	Space engineering - Spacecraft charging
EN 16603-33-11	ECSS-E-ST-33-11	Space engineering - Explosive subsystems and devices
EN 16603-50-14	ECSS-E-ST-50-14	Space engineering – Spacecraft discrete interfaces
	IEC 61000-4-2 (Edition 1.2)	Electromagnetic compatibility (EMC) - Part 4-2: Testing and measurement techniques - Electrostatic discharge immunity test

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